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Atty Docket No: SEL 139

IN THE UNITED STATES PATENT AND TRADEMARK STREET that this correspondence

In re application of: Shunpei YAMAZAKI et al Serial No: 09/386,782 Filed: August 31, 1999 For: Method Of Fabricating A Semiconductor Device Art Unit: 2812	is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on November 15, 1999 MENT COVER SHEET
Assistant Commissioner for Patents Washington, D. C. 20231 Sir:	November 11, 1999 Date
Please record the attached original document or constant of the state	5. Name and Address of Party to Whom Correspondence Concerning Document Should be Mailed: Edward D. Manzo, Esq. COOK, ALEX, McFARRON, MANZO, CUMMINGS & MEHLER, LTD. 200 West Adams Street, Suite 2850 Chicago, Illinois 60606 6. Total Number of Applications and Patents Involved:
3. Nature of Conveyance X Assignment Merger Security Agreement Change of Name Other X Execution Date: 10/21/99; 10/28/99 4. Application Number(s) or Patent number(s) (If this document is being filed together with a new application, the execution date of the application is:	7. Total Fee (37 CFR 3.41): \$40.00 7a. X Enclosed 7b. X Authorized to be Charged to Deposit Account For Any Deficiency 8. Deposit Account Number: 50/1039 (A duplicate copy of this page is attached) 9. Statement and Signature: To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.
4a. Patent Application No.(s) 09/386,782 4b. Patent No.(s)	Mark J. Murphy Name of Person Signing Signature Reg. No. 34 225 Sec. 10 10 10 10 10 10 10 10 10 10 10 10 10
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PATENT

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PATENT ASSIGNMENT COVER SHEET		
Assistant Commissioner for Patents Washington, D. C. 20231	November 11, 199	
Sir:	Date	
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Name of Conveying Party(ies): Shunpei YAMAZAKI and Hisashi OHTANI	5. Name and Address of Party to Whom Correspondence Concerning Document Should be Mailed:	
2a. Name and Address of Receiving Party(ies): Name: Semiconductor Energy Laboratory Co., Ltd. Address: 398, Hase, Atsugi-shi, Kanagawa-ken 243-0036 Japan 2b. Name and Address of Receiving Party(ies): Name: Address 3. Nature of Conveyance X Assignment Merger	Edward D. Manzo, Esq. COOK, ALEX, McFARRON, MANZO, CUMMINGS & MEHLER, LTD. 200 West Adams Street, Suite 2850 Chicago, Illinois 60606 6. Total Number of Applications and Patents Involved: _1 7. Total Fee (37 CFR 3.41): \$40.00 7a. X Enclosed 7b. X Authorized to be Charged to Deposit Account For Any Deficiency	
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4a. Patent Application No.(s) <u>09/386,782</u> 4b. Patent No.(s)	Mark J. Murphy Name of Person Signing Reg. No. 34225 Date: November 11, 1999	

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ASSIGNMENT

Identity Of The Patent Application. I am the inventor (or one joint inventor) of a patent application that I am assigning. The patent application I am assigning is entitled Method Of Fabricating A Semiconductor Device, which I executed herewith. If the patent application has already been filed, it received serial number 09/386,782 and bears a filing date of August 31, 1999

The Assignee and The Assignment. I assign my patent rights to Semiconductor Energy Laboratory Co., Ltd. a corporation organized according to the laws of Japan, having a place of business at 398, Hase, Atsugi-shi, Kanagawa-ken 243-0036 Japan (hereinafter "the Assignee"). The rights I assign are my entire right, title and interest in the invention or improvements disclosed in the patent application and any and all other applications for United States Letters Patent which I may file, either solely or jointly with others, on the invention or improvements, including all continuations, divisionals, and continuations-in-part, and in any and all United States Letters Patent which may be obtained on any of said applications, and in any reissue or extension thereof. I also assign to the Assignee all priority rights under the International Convention. I agree to execute, at the request of the Assignee, all documents in connection with any application for United States letters patent therefor.

Payment Received. I am making this assignment in consideration of One Dollar and other good and valuable consideration. I acknowledge the receipt and sufficiency of the consideration.

Authorizations. I request the U.S. Commissioner of Patents and Trademarks to issue the Letters Patent to the Assignee. I authorize the attorney(s) of record in the application to insert in this assignment document the date and serial number of the application.

Further Acts. I agree, upon the request and at the expense of the Assignee, to execute any divisional, continuation or substitute application for the invention or improvements, and any oath, declaration or affidavit relating thereto, and any application for the reissue or extension of any Letters Patent that may be granted upon the application. I agree to perform, upon request, any affirmative acts to obtain said Letters Patent of the United States and to vest in the Assignee all rights therein, so that the Letters Patent will be held and enjoyed by the Assignee, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me if this assignment had not been made.

Interference. In the event that any application or Letters Patent that I now assign becomes involved in interference, I agree to cooperate to the best of my ability in the matters of preparing and executing the preliminary statement and giving and producing evidence in support thereof.

Name: Shunpei Yamazaki

RECORDED: 11/15/1999

 $\frac{U_0}{V_0} = \frac{10/71/99}{V_0}$

Name: Hisashi Ohtani

Date

PATENT REEL: 010391 FRAME: 0812